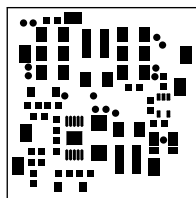
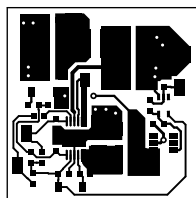


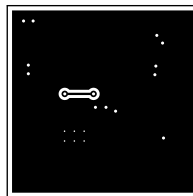
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP15022		
PLOT NAME = Top Overlay	GENERATED : 12/19/2016 12:58:04 PM	TEXAS INSTRUMENTS	



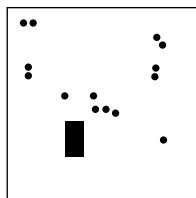
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP15022		
PLOT NAME = Top Solder Mask	GENERATED : 12/19/2016 12:58:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP15022		
PLOT NAME = Top Layer	GENERATED : 12/19/2016 12:58:06 PM	TEXAS INSTRUMENTS	

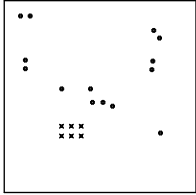


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP15022		
PLOT NAME = Bottom Layer	GENERATED : 12/19/2016 12:58:07 PM		TEXAS INSTRUMENTS

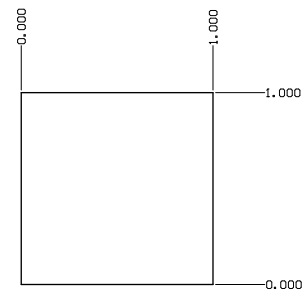


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP15022		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/19/2016 12:58:08 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✕	6	7.87mil (0.200mm)	PTH	Round
⊕	14	16.00mil (0.406mm)	PTH	Round
	20 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP15022		
PLOT NAME = Drill Drawing	GENERATED : 12/19/2016 12:58:09 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15022	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP15022		
PLOT NAME = Board Dimensions	GENERATED : 12/19/2016 12:58:10 PM		TEXAS INSTRUMENTS

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